



22nd IEEE INTERNATIONAL CONFERENCE ON
HIGH PERFORMANCE COMPUTING (HiPC 2015)
December 16-19, 2015
Bengaluru (Bangalore) | www.hipc.org



HiPC 2015 TECHNICAL PROGRAM

TREVOR MUDGE

Bredt Family Professor of Engineering, University of Michigan
THE ARCHITECTURE OF SMART PHONES

DAVID PADUA

Donald Biggar Willet Professor of Computer Science, University of Illinois at Urbana-Champaign
COMPILERS AND THE FUTURE OF HIGH PERFORMANCE COMPUTING

RAGHU RAMAKRISHNAN

Head, Big Data Engineering & Head, Cloud Information Services Lab, Microsoft
SCALE-OUT BEYOND MAP-REDUCE

HiPC 2015 will be held at the Park Plaza Bengaluru Hotel from Wednesday, December 16th through Saturday, December 19th. The conference has a history of attracting participation from leading researchers from all over the world and will feature a robust three-day technical program of peer reviewed papers and three invited keynote lectures. The main technical program will have forty-eight papers, selected from over 200 submissions, being presented in eight single track sessions. Other events include a Student Research Symposium, Workshops, and Academic Birds-of-a-Feather sessions. New in 2015, HiPC will host the Student Parallel Programming Challenge, a contest for teams of students, in India and abroad, and supported by Intel and Nvidia. For details on all events, visit the HiPC Website at www.hipc.org.

Complementing the main technical program, the HiPC workshops serve to broaden the technical scope of the conference in emerging areas of high performance computing and communication and their applications. HiPC 2015 will host four half-day workshops on December 16th; topics include:

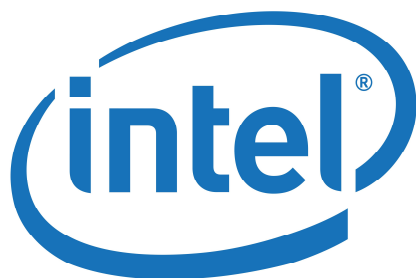
- Computational Fluid Dynamics (CFD) / •Foundations of Big Data
- InfoSymbiotics/DDDAS / •Architecture & Middleware for InfoSymbiotics/DDDAS

HiPC 2015 INDUSTRY SUPPORT

HiPC receives strong industry support from companies operating globally and also established in India. In addition to two days of industry exhibits, sponsoring partners hold industry symposiums to bring together providers and users of HPC in a forum for presenting state-of-the-art in HPC platforms and technologies. Levels of industry support include Titanium, Platinum and Gold, as well as companies who are exhibiting.

TITANIUM

PLATINUM



Co-sponsored by
IEEE Computer Society
Technical Committee on
Parallel Processing (TCPP)
& HiPC Education Trust
In cooperation with
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GOLD

